

MSKSEMI

SEMICONDUCTOR



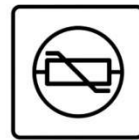
ESD



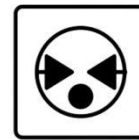
TVS



TSS



MOV



GDT

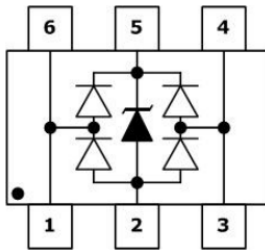


PLED

Product data sheet



SOT-666



PIN CONFIGURATON

FEATURES

- Ultra low leakage: nA level
- Operating voltage: 5V
- Low clamping voltage
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
Air discharge: ±15kV
Contact discharge: ±8kV
 - IEC61000-4-4 (EFT) 40A (5/50ns)

RoHS Compliant

APPLICATIONS

- USB 2.0 power and data line
- Set-top box and digital TV
- Digital video interface (DVI)
- Notebook Computers
- SIM Ports
- 10/100 Ethernet

Absolute Maximum Ratings (T_{amb}=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20µs)	P _{pp}	120	W
ESD per IEC 61000-4-2 (Air)	V _{ESD}	±15	Kv
ESD per IEC 61000-4-2 (Contact)		±8	
Operating Temperature Range	T _J	-55 to +125	°C
Storage Temperature Range	T _{STJ}	-55 to +150	°C

Electrical Characteristics (TA=25°C unless otherwise specified)

P/N	Marking	V _{RWM} (V)	V _{BR} (V)	I _T (mA)	V _C @1A	V _C		I _R μA (Max)	C (Pf) (Typ.)
						(Max)	(@A)		
USBLC6-2P6-MS	F	5	6	1	13	30	4	1	0.9

Characteristic Curves

Fig1. 8/20μs Pulse Waveform

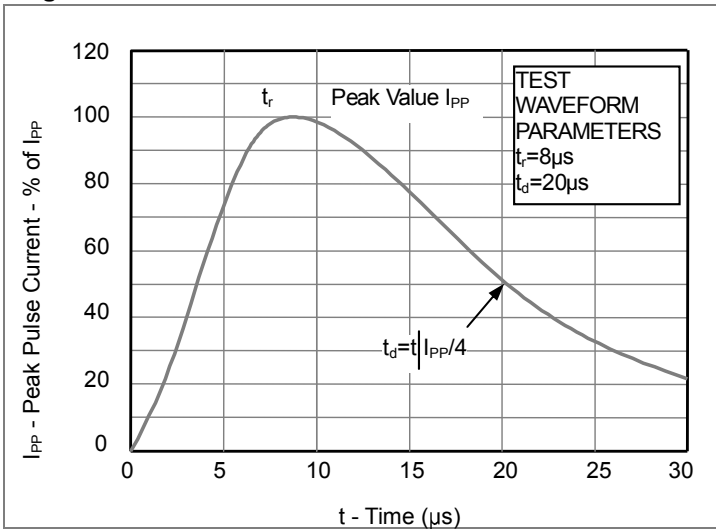


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

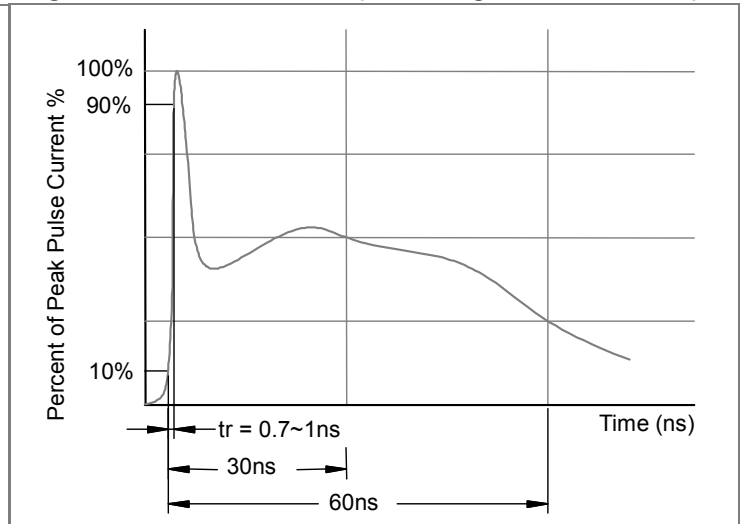
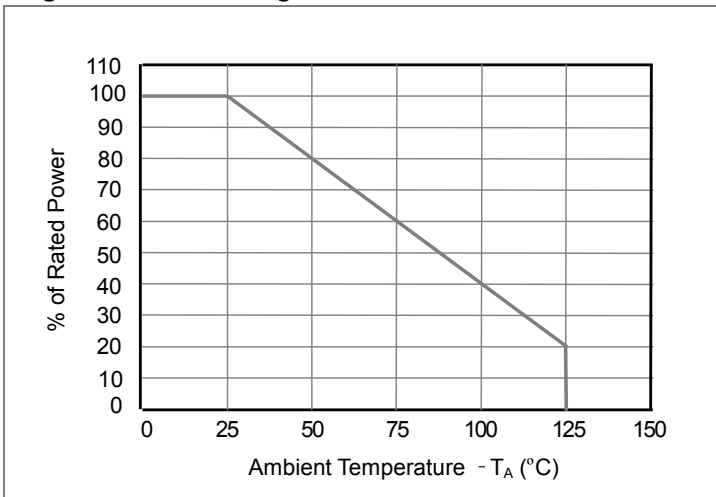
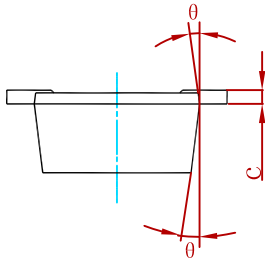
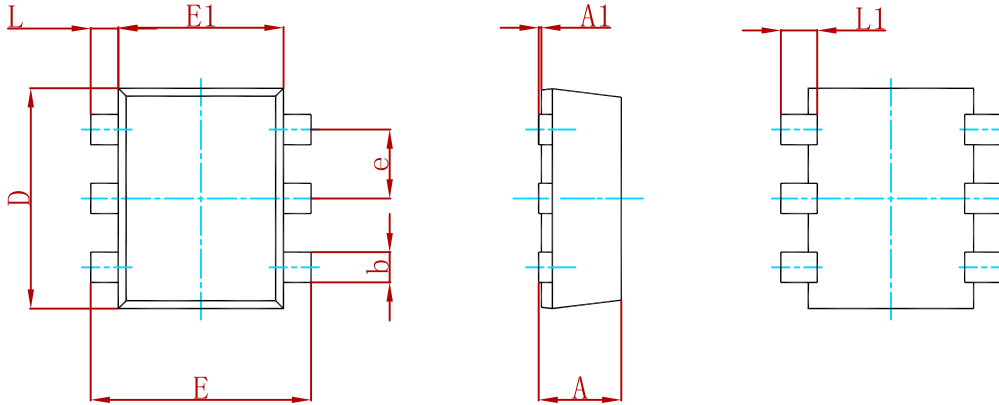


Fig3. Power Derating Curve

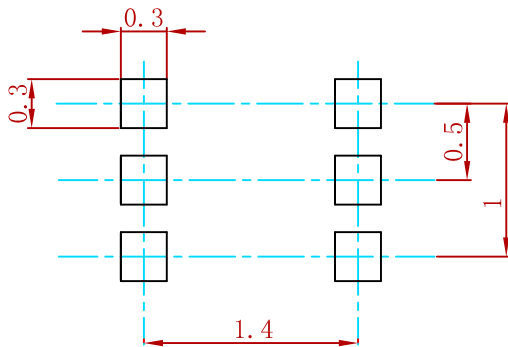


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.525	0.600	0.021	0.024
A1	0.000	0.050	0.000	0.002
e	0.450	0.550	0.018	0.022
c	0.090	0.160	0.004	0.006
D	1.500	1.700	0.059	0.067
b	0.170	0.270	0.007	0.011
E1	1.100	1.300	0.043	0.051
E	1.500	1.700	0.059	0.067
L	0.100	0.300	0.004	0.012
L1	0.200	0.400	0.008	0.016
θ	7° REF.		7° REF.	

Suggested Pad Layout



Note:
 1. Controlling dimension: in millimeters.
 2. General tolerance: ±0.05mm.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
USBLC6-2P6-MS	SOT-666	3000

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